

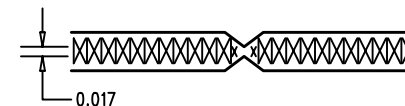
SHOWN FROM COMPONENT SIDE

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.015	70	+	PLTD
0.094	15	×	PLTD
0.035	29	□	PLTD
0.125	4	◇	PLTD
0.07	2	⊗	NPLTD
0.125	4	⊗	NPLTD
0.06	4	A	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 LINEAR TECHNOLOGY		1630 McCarthy Blvd Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE				
DRAWN			TITLE: FABRICATION DRAWING POWER-OVER-ETHERNET INTERFACE CONTROLLER			
CHECK						
DESIGN	KIM T.	03-18-04				
ENGR	DILIAN R.	03-18-04				
			SIZE	DEMO	REV.	
			A	DC671A-2 * LTC4257CS8-1	A	
SCALE = NONE			DES- 0000		SHT 1 of 1	